

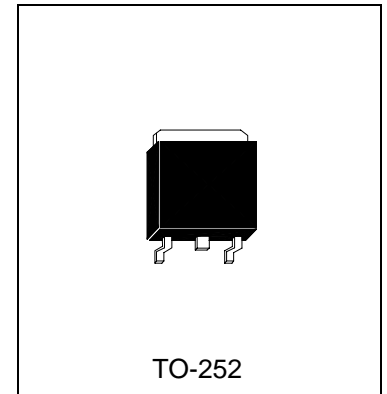


# HSB857J

PNP EPITAXIAL PLANAR TRANSISTOR

## Description

Low frequency power amplifier.



## Absolute Maximum Ratings (T<sub>A</sub>=25°C)

- Maximum Temperatures
  - Storage Temperature ..... -50~+150 °C
  - Junction Temperature ..... +150 °C Maximum
- Maximum Power Dissipation
  - Total Power Dissipation (T<sub>C</sub>=25°C) ..... 20 W
- Maximum Voltages and Currents
  - BV<sub>CBO</sub> Collector to Base Voltage ..... -60 V
  - BV<sub>CEO</sub> Collector to Emitter Voltage ..... -50 V
  - BV<sub>EBO</sub> Emitter to Base Voltage ..... -5 V
  - I<sub>C</sub> Collector Current ..... -3 A
  - I<sub>C</sub> Collector Current (I<sub>C</sub> Peak) ..... -4.5 A

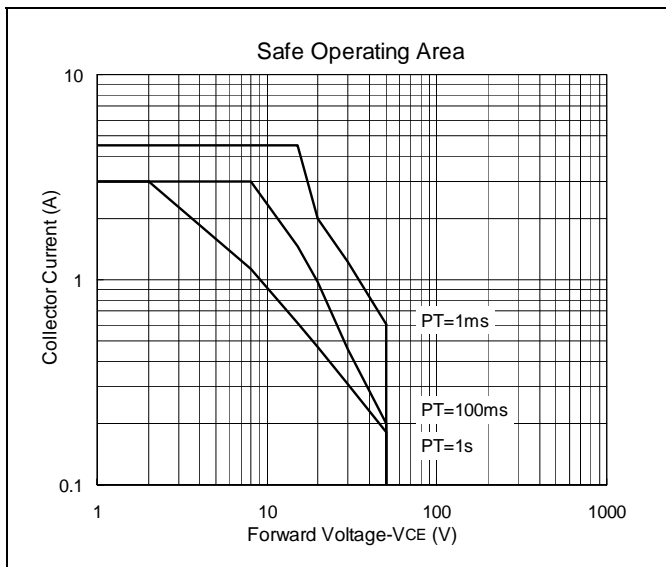
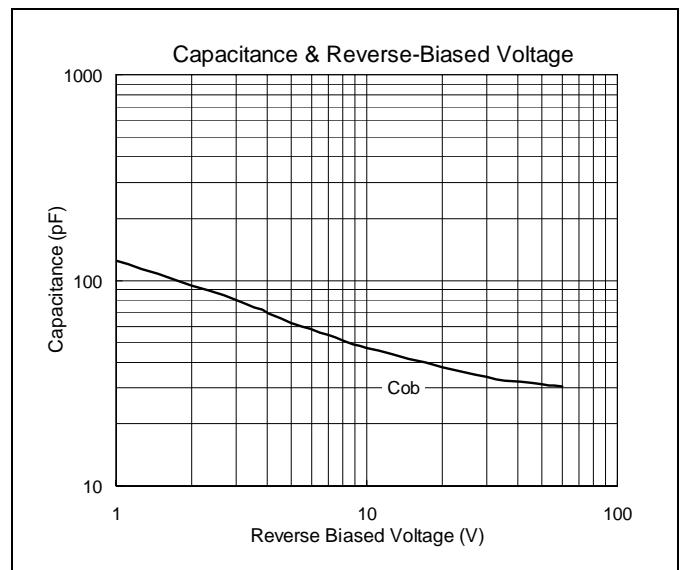
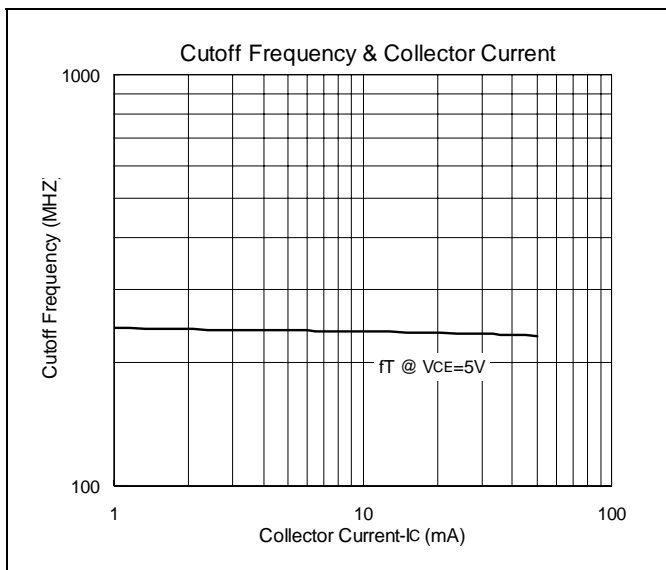
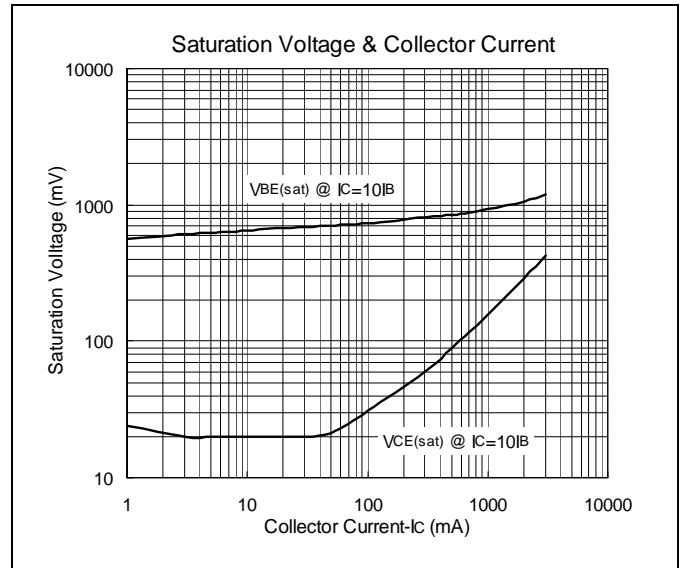
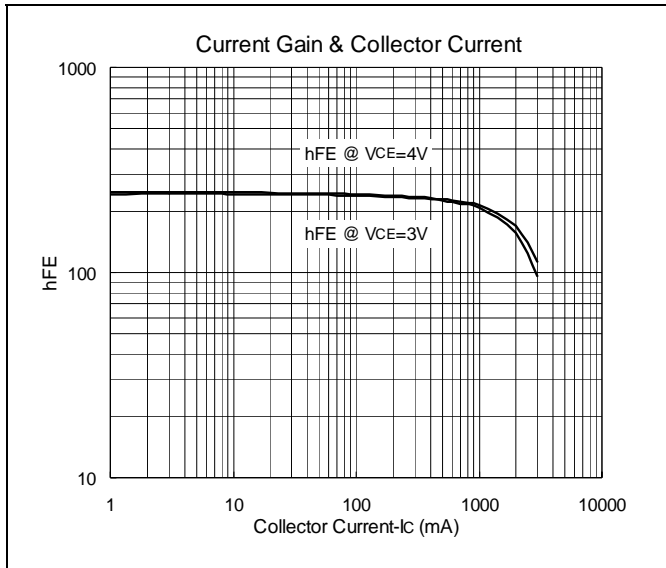
## Electrical Characteristics (T<sub>A</sub>=25°C)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BV <sub>CBO</sub>	-60	-	-	V	I <sub>C</sub> =-50uA
BV <sub>CEO</sub>	-50	-	-	V	I <sub>C</sub> =-1mA
BV <sub>EBO</sub>	-5	-	-	V	I <sub>E</sub> =-50uA
I <sub>CBO</sub>	-	-	-1	uA	V <sub>CB</sub> =-50V
I <sub>CEO</sub>	-	-	-1	uA	V <sub>CE</sub> =-40V
I <sub>EBO</sub>	-	-	-1	uA	V <sub>EB</sub> =-4V
*V <sub>CE(sat)</sub>	-	-0.3	-1	V	I <sub>C</sub> =-2A, I <sub>B</sub> =-0.2A
*V <sub>BE(sat)</sub>	-	-	-1.5	V	I <sub>C</sub> =-2A, I <sub>B</sub> =-0.2A
*h <sub>FE</sub>	170	-	400		I <sub>C</sub> =-500mA, V <sub>CE</sub> =-3V
f <sub>T</sub>	-	15	-	MHz	V <sub>CE</sub> =-5V, I <sub>C</sub> =-500mA, f=100MHz

\*Pulse Test: Pulse Width ≤380us, Duty Cycle≤2%



### Characteristics Curve





### TO-252 Dimension

3-Lead TO-252 Plastic Surface Mount Package  
HSMC Package Code: J

**Marking:**

Pb Free Mark  
 Pb-Free: "●" (Note)  
 Normal: None

Note: Green label is used for pb-free packing  
 Pin Style: 1.Base 2.Collector 3.Emitter

**Material:**

- Lead solder plating: Sn60/Pb40 (Normal), Sn/3.0Ag/0.5Cu or Pure-Tin (Pb-free)
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0

DIM	Min.	Max.
A	6.35	6.80
C	4.80	5.50
F	1.30	1.70
G	5.40	6.25
H	2.20	3.00
L	0.40	0.90
M	2.20	2.40
N	0.90	1.50
a1	0.40	0.65
a2	-	*2.30
a5	0.65	1.05

\*: Typical, Unit: mm

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- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0

DIM	Min.	Max.
A	6.40	6.80
B	-	6.00
C	5.04	5.64
D	-	*4.34
E	0.40	0.80
F	0.50	0.90
G	5.90	6.30
H	2.50	2.90
I	9.20	9.80
J	0.60	1.00
K	-	0.96
L	0.66	0.86
M	2.20	2.40
N	0.70	1.10
O	0.82	1.22
a1	0.40	0.60
a2	2.10	2.50
y1	-	5°
y2	-	3°

\*: Typical, Unit: mm

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#### Head Office And Factory:

- **Head Office** (Hi-Sincerity Microelectronics Corp.): 10F., No. 61, Sec. 2, Chung-Shan N. Rd. Taipei Taiwan R.O.C.  
 Tel: 886-2-25212056 Fax: 886-2-25632712, 25368454
- **Factory 1:** No. 38, Kuang Fu S. Rd., Fu-Kou Hsin-Chu Industrial Park Hsin-Chu Taiwan. R.O.C  
 Tel: 886-3-5983621~5 Fax: 886-3-5982931



### Soldering Methods for HSMC's Products

1. Storage environment: Temperature=10°C~35°C Humidity=65%±15%
2. Reflow soldering of surface-mount devices



Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Average ramp-up rate ( $T_L$ to $T_P$ )	$<3^{\circ}\text{C}/\text{sec}$	$<3^{\circ}\text{C}/\text{sec}$
Preheat		
- Temperature Min ( $T_{Smin}$ )	100°C	150°C
- Temperature Max ( $T_{Smax}$ )	150°C	200°C
- Time (min to max) ( $t_s$ )	60~120 sec	60~180 sec
$T_{Smax}$ to $T_L$		
- Ramp-up Rate	$<3^{\circ}\text{C}/\text{sec}$	$<3^{\circ}\text{C}/\text{sec}$
Time maintained above:		
- Temperature ( $T_L$ )	183°C	217°C
- Time ( $t_L$ )	60~150 sec	60~150 sec
Peak Temperature ( $T_P$ )	240°C +0/-5°C	260°C +0/-5°C
Time within 5°C of actual Peak Temperature ( $t_p$ )	10~30 sec	20~40 sec
Ramp-down Rate	$<6^{\circ}\text{C}/\text{sec}$	$<6^{\circ}\text{C}/\text{sec}$
Time 25°C to Peak Temperature	$<6$ minutes	$<8$ minutes

### 3. Flow (wave) soldering (solder dipping)

Products	Peak temperature	Dipping time
Pb devices.	245°C ±5°C	5sec ±1sec
Pb-Free devices.	260°C +0/-5°C	5sec ±1sec